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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, LCD, POR, PWM, WDT
Number of I/O	66
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f8493t-i-pt

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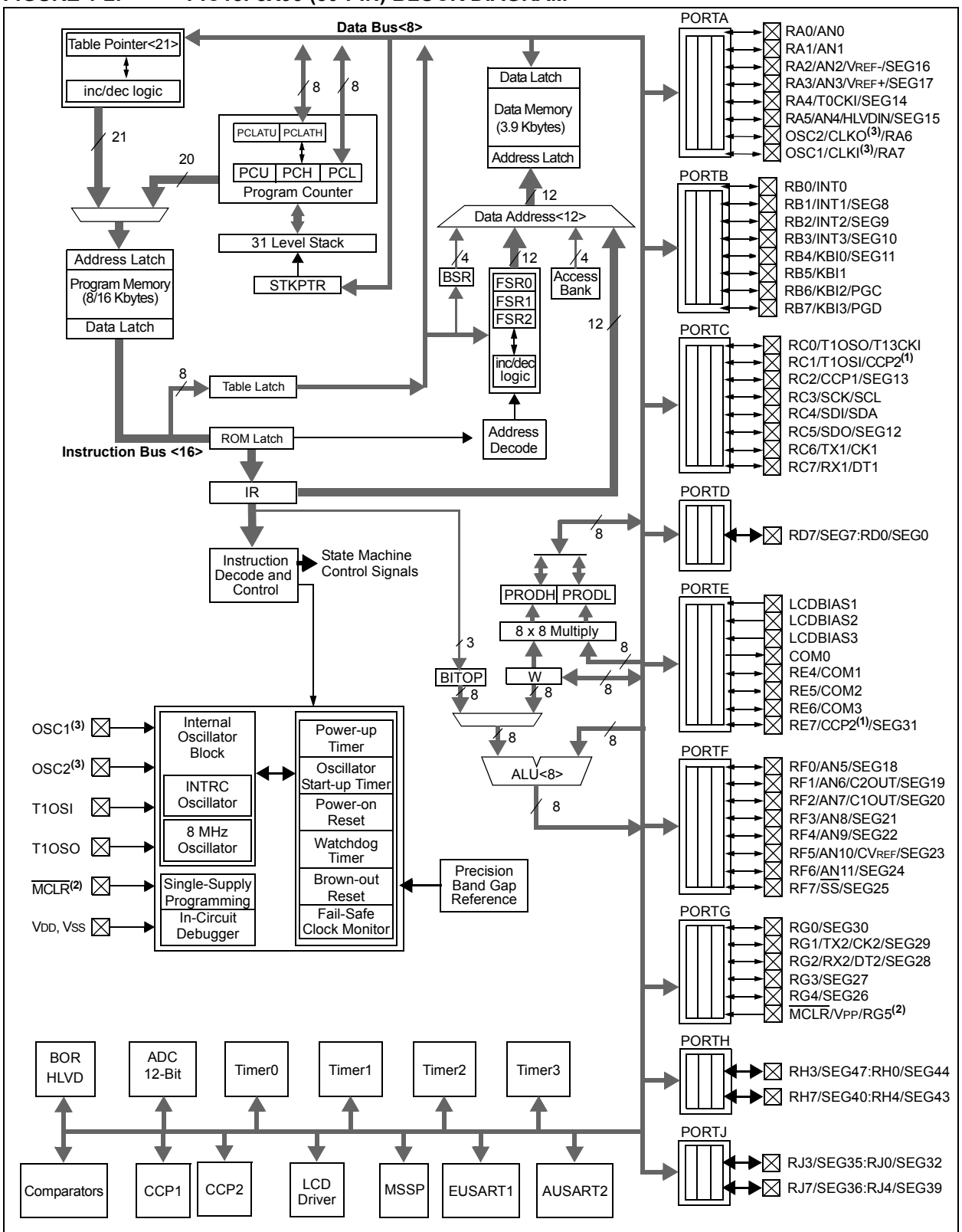
FIGURE 1-2: PIC18F8X93 (80-PIN) BLOCK DIAGRAM



Note 1: CCP2 is multiplexed with RC1 when Configuration bit, CCP2MX, is set and RE7 when CCP2MX is not set.

2: RG5 is only available when $\overline{\text{MCLR}}$ functionality is disabled.

3: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O. For additional information, see **Section 2.0 "Oscillator Configurations"** of the "PIC18F6390/6490/8390/8490 *Data Sheet"* (DS39629).

TABLE 1-2: PIC18F6X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT0	48			
RB0		I/O	TTL	Digital I/O.
INT0		I	ST	External Interrupt 0.
RB1/INT1/SEG8	47			
RB1		I/O	TTL	Digital I/O.
INT1		I	ST	External Interrupt 1.
SEG8		O	Analog	SEG8 output for LCD.
RB2/INT2/SEG9	46			
RB2		I/O	TTL	Digital I/O.
INT2		I	ST	External Interrupt 2.
SEG9		O	Analog	SEG9 output for LCD.
RB3/INT3/SEG10	45			
RB3		I/O	TTL	Digital I/O.
INT3		I	ST	External Interrupt 3.
SEG10		O	Analog	SEG10 output for LCD.
RB4/KBI0/SEG11	44			
RB4		I/O	TTL	Digital I/O.
KBI0		I	TTL	Interrupt-on-change pin.
SEG11		O	Analog	SEG11 output for LCD.
RB5/KBI1	43			
RB5		I/O	TTL	Digital I/O.
KBI1		I	TTL	Interrupt-on-change pin.
RB6/KBI2/PGC	42			
RB6		I/O	TTL	Digital I/O.
KBI2		I	TTL	Interrupt-on-change pin.
PGC		I/O	ST	In-Circuit Debugger and ICSP™ programming clock pin.
RB7/KBI3/PGD	37			
RB7		I/O	TTL	Digital I/O.
KBI3		I	TTL	Interrupt-on-change pin.
PGD		I/O	ST	In-Circuit Debugger and ICSP programming data pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-2: PIC18F6X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTD is a bidirectional I/O port.
RD0/SEG0	58			
RD0		I/O	ST	Digital I/O.
SEG0		O	Analog	SEG0 output for LCD.
RD1/SEG1	55			
RD1		I/O	ST	Digital I/O.
SEG1		O	Analog	SEG1 output for LCD.
RD2/SEG2	54			
RD2		I/O	ST	Digital I/O.
SEG2		O	Analog	SEG2 output for LCD.
RD3/SEG3	53			
RD3		I/O	ST	Digital I/O.
SEG3		O	Analog	SEG3 output for LCD.
RD4/SEG4	52			
RD4		I/O	ST	Digital I/O.
SEG4		O	Analog	SEG4 output for LCD.
RD5/SEG5	51			
RD5		I/O	ST	Digital I/O.
SEG5		O	Analog	SEG5 output for LCD.
RD6/SEG6	50			
RD6		I/O	ST	Digital I/O.
SEG6		O	Analog	SEG6 output for LCD.
RD7/SEG7	49			
RD7		I/O	ST	Digital I/O.
SEG7		O	Analog	SEG7 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-2: PIC18F6X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTE is a bidirectional I/O port.
LCDBIAS1	2			
LCDBIAS1		I	Analog	BIAS1 input for LCD.
LCDBIAS2	1			
LCDBIAS2		I	Analog	BIAS2 input for LCD.
LCDBIAS3	64			
LCDBIAS3		I	Analog	BIAS3 input for LCD.
COM0	63			
COM0		O	Analog	COM0 output for LCD.
RE4/COM1	62			
RE4		I/O	ST	Digital I/O.
COM1		O	Analog	COM1 output for LCD.
RE5/COM2	61			
RE5		I/O	ST	Digital I/O.
COM2		O	Analog	COM2 output for LCD.
RE6/COM3	60			
RE6		I/O	ST	Digital I/O.
COM3		O	Analog	COM3 output for LCD.
RE7/CCP2/SEG31	59			
RE7		I/O	ST	Digital I/O.
CCP2(2)		I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
SEG31		O	Analog	SEG31 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-2: PIC18F6X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTG is a bidirectional I/O port.
RG0/SEG30	3			
RG0		I/O	ST	Digital I/O.
SEG30		O	Analog	SEG30 output for LCD.
RG1/TX2/CK2/SEG29	4			
RG1		I/O	ST	Digital I/O.
TX2		O	—	AUSART2 asynchronous transmit.
CK2		I/O	ST	AUSART2 synchronous clock (see related RX2/DT2).
SEG29		O	Analog	SEG29 output for LCD.
RG2/RX2/DT2/SEG28	5			
RG2		I/O	ST	Digital I/O.
RX2		I	ST	AUSART2 asynchronous receive.
DT2		I/O	ST	AUSART2 synchronous data (see related TX2/CK2).
SEG28		O	Analog	SEG28 output for LCD.
RG3/SEG27	6			
RG3		I/O	ST	Digital I/O.
SEG27		O	Analog	SEG27 output for LCD.
RG4/SEG26	8			
RG4		I/O	ST	Digital I/O.
SEG26		O	Analog	SEG26 output for LCD.
RG5				See $\overline{MCLR}$/VPP/RG5 pin.
VSS	9, 25, 41, 56	P	—	Ground reference for logic and I/O pins.
VDD	10, 26, 38, 57	P	—	Positive supply for logic and I/O pins.
AVSS	20	P	—	Ground reference for analog modules.
AVDD	19	P	—	Positive supply for analog modules.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F8X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTD is a bidirectional I/O port.
RD0/SEG0	72			
RD0		I/O	ST	Digital I/O.
SEG0		O	Analog	SEG0 output for LCD.
RD1/SEG1	69			
RD1		I/O	ST	Digital I/O.
SEG1		O	Analog	SEG1 output for LCD.
RD2/SEG2	68			
RD2		I/O	ST	Digital I/O.
SEG2		O	Analog	SEG2 output for LCD.
RD3/SEG3	67			
RD3		I/O	ST	Digital I/O.
SEG3		O	Analog	SEG3 output for LCD.
RD4/SEG4	66			
RD4		I/O	ST	Digital I/O.
SEG4		O	Analog	SEG4 output for LCD.
RD5/SEG5	65			
RD5		I/O	ST	Digital I/O.
SEG5		O	Analog	SEG5 output for LCD.
RD6/SEG6	64			
RD6		I/O	ST	Digital I/O.
SEG6		O	Analog	SEG6 output for LCD.
RD7/SEG7	63			
RD7		I/O	ST	Digital I/O.
SEG7		O	Analog	SEG7 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F8X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTE is a bidirectional I/O port.
LCDBIAS1	4			
LCDBIAS1		I	Analog	BIAS1 input for LCD.
LCDBIAS2	3			
LCDBIAS2		I	Analog	BIAS2 input for LCD.
LCDBIAS3	78			
LCDBIAS3		I	Analog	BIAS3 input for LCD.
COM0	77			
COM0		O	Analog	COM0 output for LCD.
RE4/COM1	76			
RE4		I/O	ST	Digital I/O.
COM1		O	Analog	COM1 output for LCD.
RE5/COM2	75			
RE5		I/O	ST	Digital I/O.
COM2		O	Analog	COM2 output for LCD.
RE6/COM3	74			
RE6		I/O	ST	Digital I/O.
COM3		O	Analog	COM3 output for LCD.
RE7/CCP2/SEG31	73			
RE7		I/O	ST	Digital I/O.
CCP2(2)		I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
SEG31		O	Analog	SEG31 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F8X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTJ is a bidirectional I/O port.
RJ0/SEG32	62			
RJ0		I/O	ST	Digital I/O.
SEG32		O	Analog	SEG32 output for LCD.
RJ1/SEG33	61			
RJ1		I/O	ST	Digital I/O.
SEG33		O	Analog	SEG33 output for LCD.
RJ2/SEG34	60			
RJ2		I/O	ST	Digital I/O.
SEG34		O	Analog	SEG34 output for LCD.
RJ3/SEG35	59			
RJ3		I/O	ST	Digital I/O.
SEG35		O	Analog	SEG35 output for LCD.
RJ4/SEG39	39			
RJ4		I/O	ST	Digital I/O.
SEG39		O	Analog	SEG39 output for LCD.
RJ5/SEG38	40			
RJ5		I/O	ST	Digital I/O
SEG38		O	Analog	SEG38 output for LCD.
RJ6/SEG37	41			
RJ6		I/O	ST	Digital I/O.
SEG37		O	Analog	SEG37 output for LCD.
RJ7/SEG36	42			
RJ7		I/O	ST	Digital I/O.
SEG36		O	Analog	SEG36 output for LCD.
VSS	11, 31, 51, 70	P	—	Ground reference for logic and I/O pins.
VDD	12, 32, 48, 71	P	—	Positive supply for logic and I/O pins.
AVSS	26	P	—	Ground reference for analog modules.
AVDD	25	P	—	Positive supply for analog modules.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

REGISTER 2-2: ADCON1: A/D CONTROL REGISTER 1

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **VCFG<1:0>:** Voltage Reference Configuration bits

	A/D VREF+	**A/D VREF-**
00	AVDD	AVSS
01	External VREF+	AVSS
10	AVDD	External VREF-
11	External VREF+	External VREF-

bit 3-0 **PCFG<3:0>:** A/D Port Configuration Control bits

PCFG<3:0>	**AN11**	**AN10**	**AN9**	**AN8**	**AN7**	**AN6**	**AN5**	**AN4**	**AN3**	**AN2**	**AN1**	**AN0**
0000	A	A	A	A	A	A	A	A	A	A	A	A
0001	A	A	A	A	A	A	A	A	A	A	A	A
0010	A	A	A	A	A	A	A	A	A	A	A	A
0011	A	A	A	A	A	A	A	A	A	A	A	A
0100	D	A	A	A	A	A	A	A	A	A	A	A
0101	D	D	A	A	A	A	A	A	A	A	A	A
0110	D	D	D	A	A	A	A	A	A	A	A	A
0111	D	D	D	D	A	A	A	A	A	A	A	A
1000	D	D	D	D	D	A	A	A	A	A	A	A
1001	D	D	D	D	D	D	A	A	A	A	A	A
1010	D	D	D	D	D	D	D	A	A	A	A	A
1011	D	D	D	D	D	D	D	D	A	A	A	A
1100	D	D	D	D	D	D	D	D	D	A	A	A
1101	D	D	D	D	D	D	D	D	D	D	A	A
1110	D	D	D	D	D	D	D	D	D	D	D	A
1111	D	D	D	D	D	D	D	D	D	D	D	D

A = Analog input D = Digital I/O

The value in the ADRESH:ADRESL registers is unknown following Power-on and Brown-out Resets and is not affected by any other Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see **Section 2.1 "A/D Acquisition Requirements"**. After this acquisition time has elapsed, the A/D conversion can be started. An acquisition time can be programmed to occur between setting the GO/$\overline{\text{DONE}}$ bit and the actual start of the conversion.

The following steps should be followed to perform an A/D conversion:

1. Configure the A/D module:
   - Configure analog pins, voltage reference and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D acquisition time (ADCON2)
   - Select A/D conversion clock (ADCON2)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set GIE bit
3. Wait the required acquisition time (if required).
4. Start conversion:
   - Set GO/$\overline{\text{DONE}}$ bit (ADCON0<1>)
5. Wait for A/D conversion to complete by either:
   - Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared

   OR
   - Waiting for the A/D interrupt
6. Read A/D Result registers (ADRESH:ADRESL); clear bit, ADIF, if required.
7. For the next conversion, go to Step 1 or Step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2 TAD is required before the next acquisition starts.

FIGURE 2-2: A/D TRANSFER FUNCTION

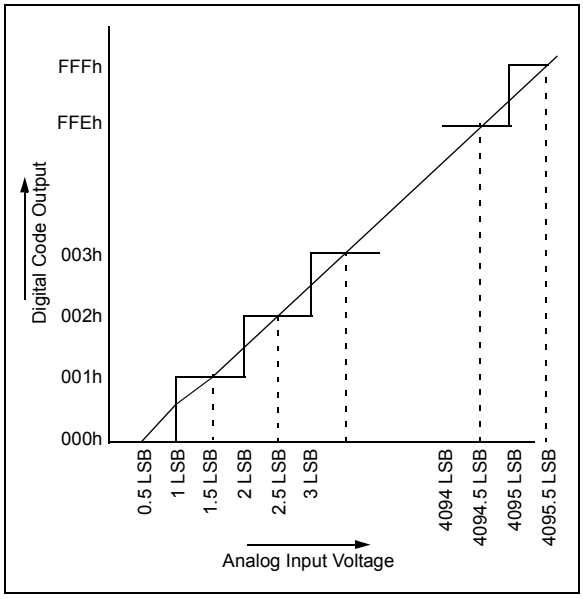
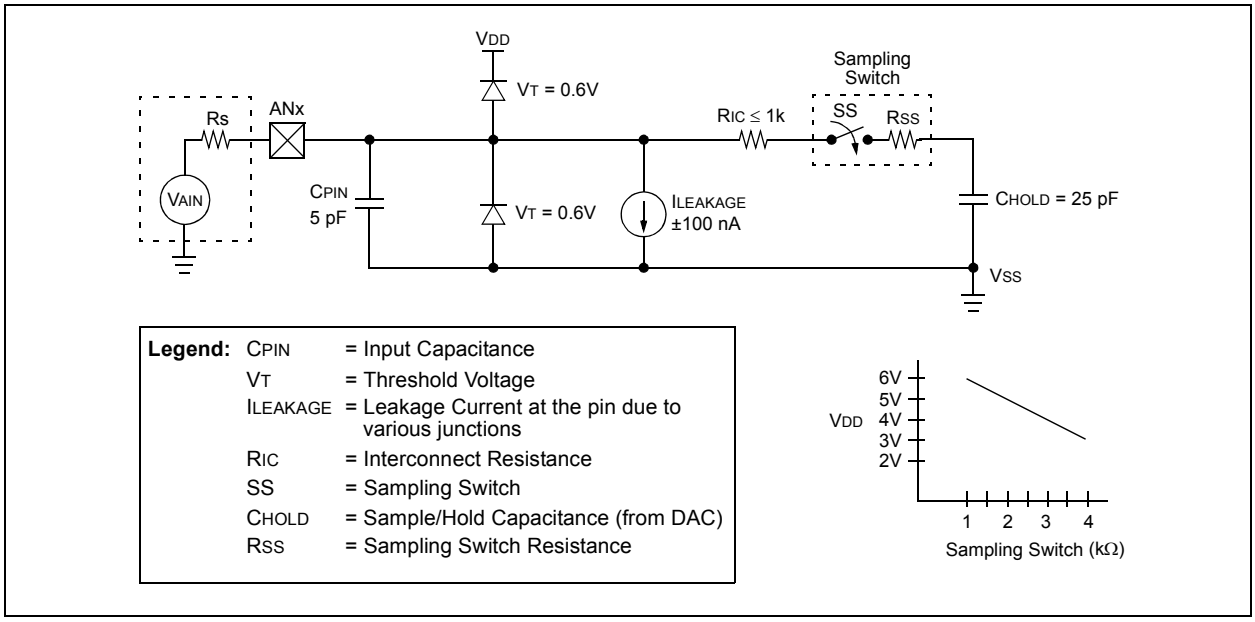


FIGURE 2-3: ANALOG INPUT MODEL



2.1 A/D Acquisition Requirements

For the A/D Converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 2-3. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor, CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ**. After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 2-1 may be used. This equation assumes that 1/2 LSb error is used (4096 steps for the 12-bit A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Equation 2-3 shows the calculation of the minimum required acquisition time, TACQ. This calculation is based on the following application system assumptions:

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
VDD	=	3V → Rss = 4 kΩ
Temperature	=	85°C (system max.)

EQUATION 2-1: A/D ACQUISITION TIME

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$

EQUATION 2-2: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/4096)) \cdot (1 - e^{(-T_C/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$$
or
$$T_C = (C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/4096)$$

EQUATION 2-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$$
$$T_{AMP} = 0.2\ \mu s$$
$$T_{COFF} = (\text{Temp} - 25°C)(0.02\ \mu s/°C)$$
$$(85°C - 25°C)(0.02\ \mu s/°C)$$
$$1.2\ \mu s$$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, $T_{COFF} = 0\ \mu s$.

$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/4096)\ \mu s$$
$$-(25\ pF)(1\ k\Omega + 4\ k\Omega + 2.5\ k\Omega) \ln(0.0002441)\ \mu s$$
$$1.56\ \mu s$$
$$T_{ACQ} = 0.2\ \mu s + 1.56\ \mu s + 1.2\ \mu s$$
$$2.96\ \mu s$$

2.6 A/D Conversions

Figure 2-4 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set and the ACQT<2:0> bits are cleared. A conversion is started after the following instruction to allow entry into Sleep mode before the conversion begins.

Figure 2-5 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set, the ACQT<2:0> bits are set to '010' and a 4 TAD acquisition time has been selected before the conversion starts.

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The A/D Result register pair will *not* be updated with the partially completed A/D conversion sample. This means the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers).

After the A/D conversion is completed or aborted, a 2 TAD wait is required before the next acquisition can be started. After this wait, acquisition on the selected channel is automatically started.

Note:	The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D. Code should wait at least 2 μs after enabling the A/D before beginning an acquisition and conversion cycle.

2.7 Discharge

The discharge phase is used to initialize the value of the holding capacitor. The array is discharged before every sample. This feature helps to optimize the unity gain amplifier, as the circuit always needs to charge the capacitor array, rather than charge/discharge based on previous measure values.

FIGURE 2-4: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 000, TACQ = 0)

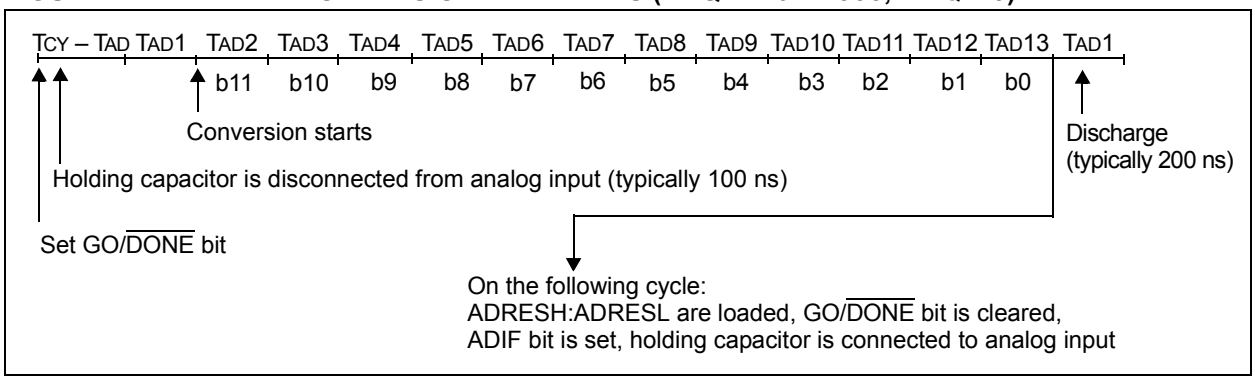
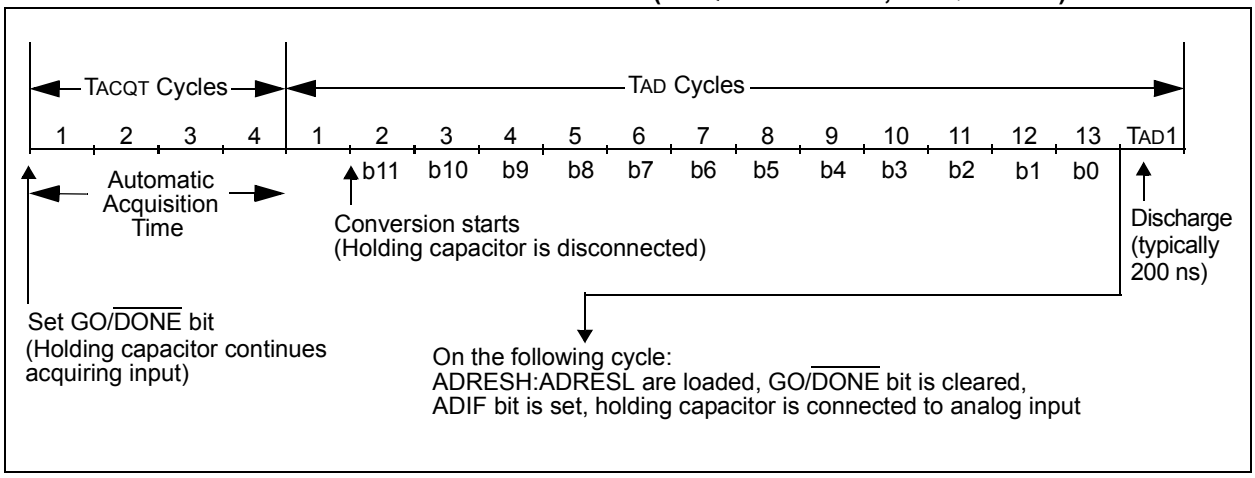


FIGURE 2-5: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 010, TACQ = 4 TAD)



2.8 Use of the ECCP2 Trigger

An A/D conversion can be started by the Special Event Trigger of the ECCP2 module. This requires that the CCP2M<3:0> bits (CCP2CON<3:0>) be programmed as '1011' and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/$\overline{\text{DONE}}$ bit will be set, starting the A/D acquisition and conversion, and the Timer1 (or Timer3) counter will be reset to zero. Timer1 (or Timer3) is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving ADRESH:ADRESL to the desired location). The appropriate analog input channel must be selected and the minimum acquisition period is either timed by the user, or an appropriate TACQ time selected before the Special Event Trigger sets the GO/$\overline{\text{DONE}}$ bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), the Special Event Trigger will be ignored by the A/D module, but will still reset the Timer1 (or Timer3) counter.

TABLE 2-2: REGISTERS ASSOCIATED WITH A/D OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	(3)
PIR1	—	ADIF	RC1IF	TX1IF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	(3)
PIE1	—	ADIE	RC1IE	TX1IE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	(3)
IPR1	—	ADIP	RC1IP	TX1IP	SSP1IP	CCP1IP	TMR2IP	TMR1IP	(3)
PIR2	OSCFIF	CMIF	—	—	BCL1IF	HLVDIF	TMR3IF	CCP2IF	(3)
PIE2	OSCFIE	CMIE	—	—	BCL1IE	HLVDIE	TMR3IE	CCP2IE	(3)
IPR2	OSCFIP	CMIP	—	—	BCL1IP	HLVDIP	TMR3IP	CCP2IP	(3)
ADRESH	A/D Result Register High Byte								(3)
ADRESL	A/D Result Register Low Byte								(3)
ADCON0	—	—	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	(3)
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	(3)
ADCON2	ADFM	—	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0	(3)
TRISA	TRISA7(1)	TRISA6(1)	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	(3)
TRISF	TRISF7	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	(3)
TRISH(2)	TRISH7	TRISH6	TRISH5	TRISH4	TRISH3	TRISH2	TRISH1	TRISH0	(3)

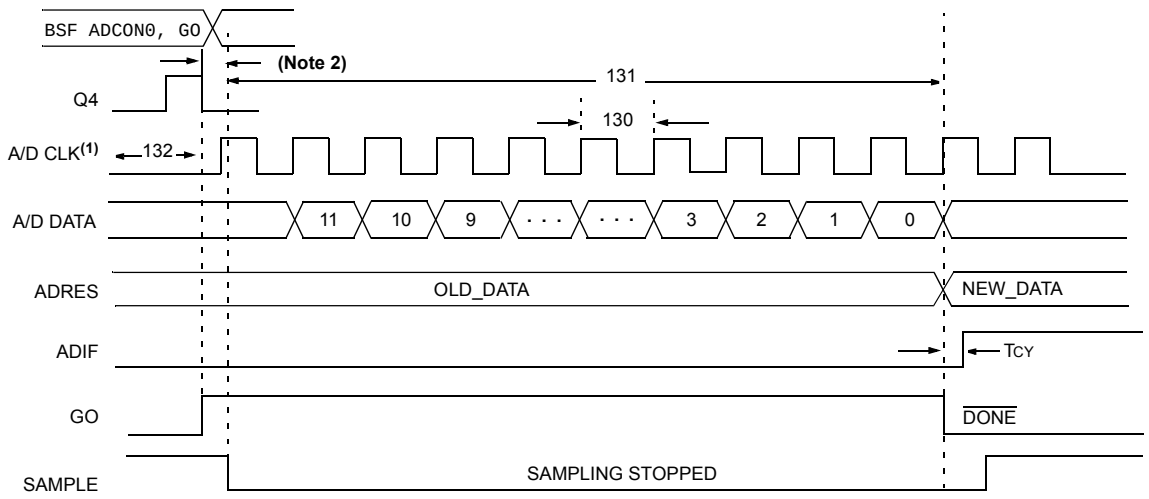
Legend: — = unimplemented, read as '0'. Shaded cells are not used for A/D conversion.

Note 1: PORTA<7:6> and their direction bits are individually configured as port pins based on various primary oscillator modes. When disabled, these bits read as '0'.

2: These registers are not implemented on 64-pin devices.

3: For these Reset values, see the *"*PIC18F6390/6490/8390/8490 *Data Sheet"* (DS39629).

FIGURE 4-3: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

2: This is a minimal RC delay (typically 100 ns), which also disconnects the holding capacitor from the analog input.

TABLE 4-2: A/D CONVERSION REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
130	TAD	A/D Clock Period	PIC18**F**XXXX	0.8	12.5(1)	µs	TOSC based, VREF ≥ 3.0V
			PIC18**LF**XXXX	1.4	25.0(1)	µs	VDD = 3.0V; TOSC based, VREF full range
			PIC18**F**XXXX	—	1	µs	A/D RC mode
			PIC18**LF**XXXX	—	3	µs	VDD = 3.0V; A/D RC mode
131	TCNV	Conversion Time (not including acquisition time)(2)		13	14	TAD	
132	TACQ	Acquisition Time(3)		1.4	—	µs	
135	TSWC	Switching Time from Convert → Sample		—	**(Note 4)**		
137	TDIS	Discharge Time		0.2	—	µs	

Note 1: The time of the A/D clock period is dependent on the device frequency and the TAD clock divider.

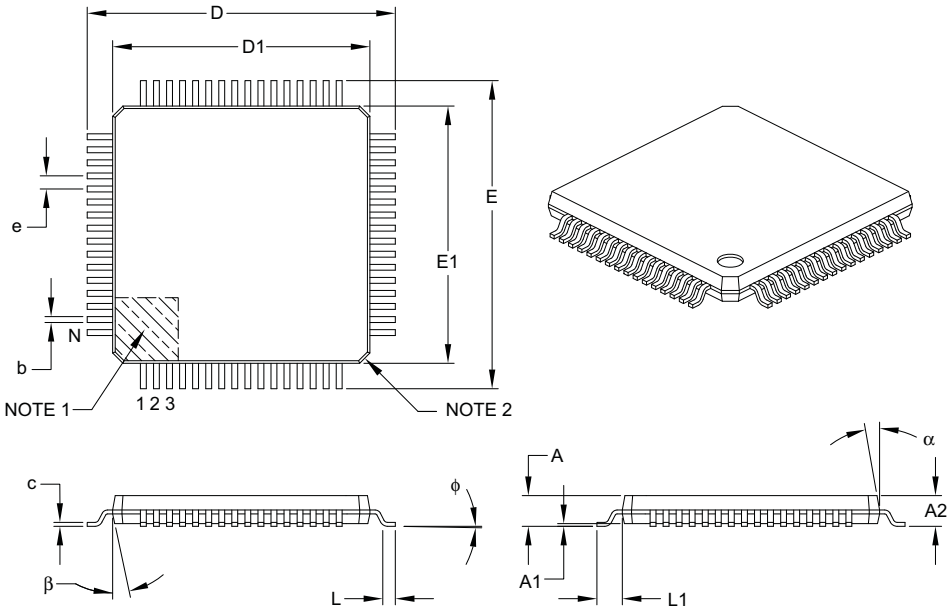
2: ADRES registers may be read on the following TCY cycle.

3: The time for the holding capacitor to acquire the "New" input voltage when the voltage changes full scale after the conversion (VDD to VSS or VSS to VDD). The source impedance (RS) on the input channels is 50Ω.

4: On the following cycle of the device clock.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

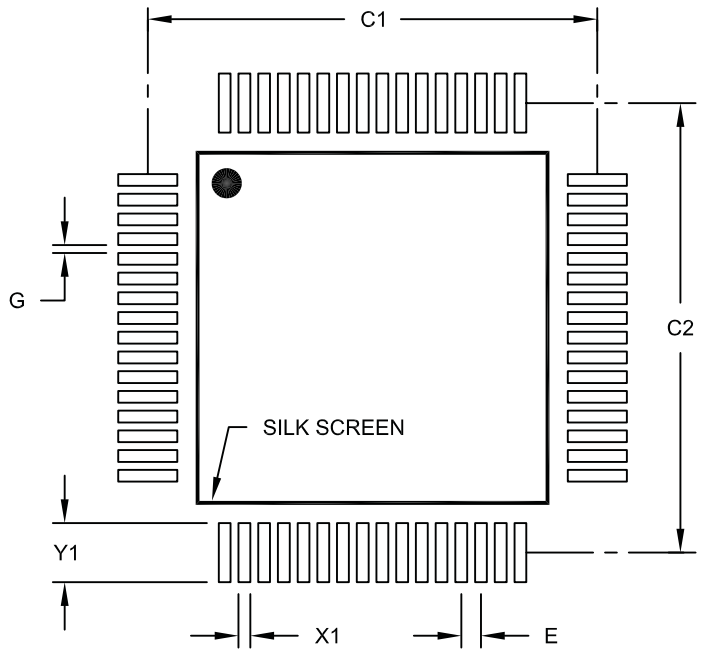
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085A

APPENDIX A: REVISION HISTORY

Revision A (September 2007)

Original data sheet for the PIC18F6393/6493/8393/8493 devices.

Revision B (October 2009)

Removed “Preliminary” marking.

Revision C (August 2010)

Changes and additions were made to the **“Power-Managed Modes”**, **“Flexible Oscillator Structure”, “Peripheral Highlights”** and **“Special Microcontroller Features”** sections. Changes were made to Figure 1-1, Figure 1-2, Table 1-2 and Table 1-3, including edits to the legends of those tables. New text has replaced all in **2.4 “Operation in Power-Managed Modes”**. Corrections have been made to **4.0 “Electrical Characteristics”**. The extended temperature has been removed from the **“Product Identification System”** information. New packaging diagrams were added because the diagrams referenced in the document, *“*PIC18F6390/6490/8390/8490 *Data Sheet”* (DS39629), have not been updated. Minor typographical edits throughout the document.

APPENDIX B: DEVICE DIFFERENCES

The differences between the devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Features	PIC18F6393	PIC18F6493	PIC18F8393	PIC18F8493
Number of Pixels the LCD Driver Can Drive	128 (4 x 32)	128 (4 x 32)	192 (4 x 48)	192 (4 x 48)
I/O Ports	Ports A, B, C, D, E, F, G	Ports A, B, C, D, E, F, G	Ports A, B, C, D, E, F, G, H, J	Ports A, B, C, D, E, F, G, H, J
Flash Program Memory	8 Kbytes	16 Kbytes	8 Kbytes	16 Kbytes
Packages	64-Pin TQFP	64-Pin TQFP	80-Pin TQFP	80-Pin TQFP

APPENDIX E: MIGRATION FROM MID-RANGE TO ENHANCED DEVICES

A detailed discussion of the differences between the mid-range MCU devices (i.e., PIC16CXXX) and the enhanced devices (i.e., PIC18FXXX) is provided in *AN716, "Migrating Designs from PIC16C74A/74B to PIC18C442"*. The changes discussed, while device-specific, are generally applicable to all mid-range to enhanced device migrations.

This Application Note is available as Literature Number DS00716.

APPENDIX F: MIGRATION FROM HIGH-END TO ENHANCED DEVICES

A detailed discussion of the migration pathway, and differences between the high-end MCU devices (i.e., PIC17CXXX), and the enhanced devices (i.e., PIC18FXXX) is provided in *AN726, "PIC17CXXX to PIC18CXXX Migration"*. This Application Note is available as Literature Number DS00726.

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